

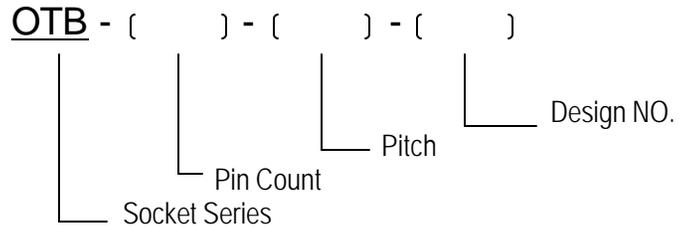
# BGA/LGA

# BALL/LAND GRID ARRAY

## Applicable IC/BGA

## OPEN TOP TYPE SOCKETS

### ORDERING PROCEDURE

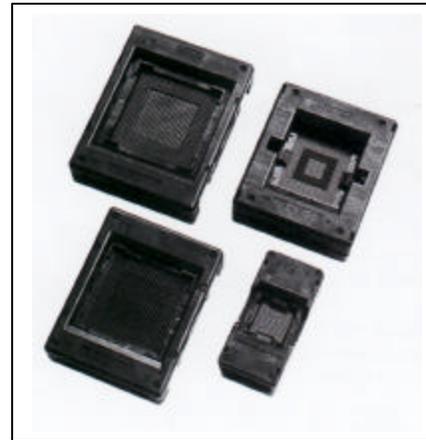


### SPECIFICATIONS

- Contact resistance: Initial 50m $\Omega$  (At 10mA)
- Maximum voltage: AC700V RMS (for 1 minute)
- Insulation resistance: 1,000M $\Omega$  or higher (At DC 500V)
- Rated current: 1A
- Operating temperature range: -60°C ~ +150°C
- Terminal strength against pulling: 0.5kg (1 minute)
- Insertion: Min. 10,000 times (Mechanical)

### MATERIAL

- Body: PEI, PES
- Contact: BeCu, Au plating (Ni-base)



## APPLICABLE IC DIMENSIONS & SOCKET DIMENSIONS

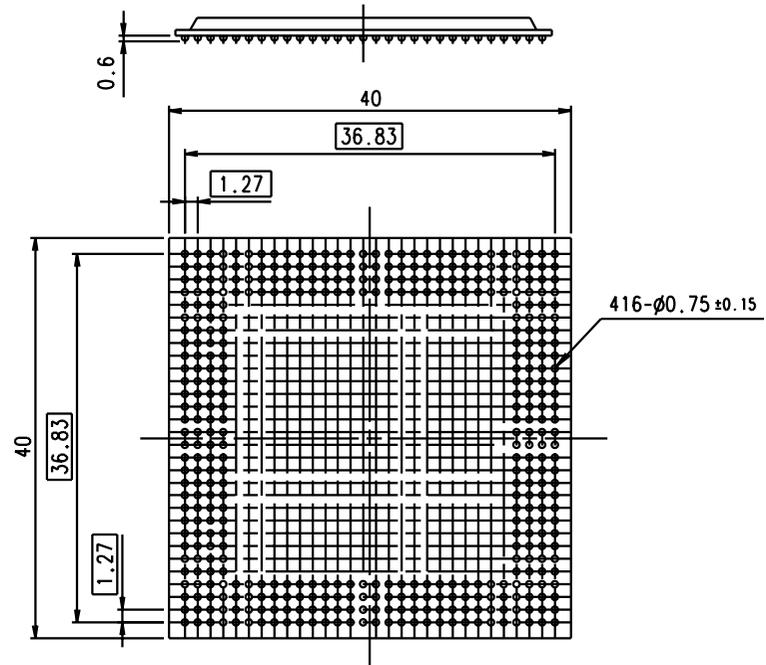
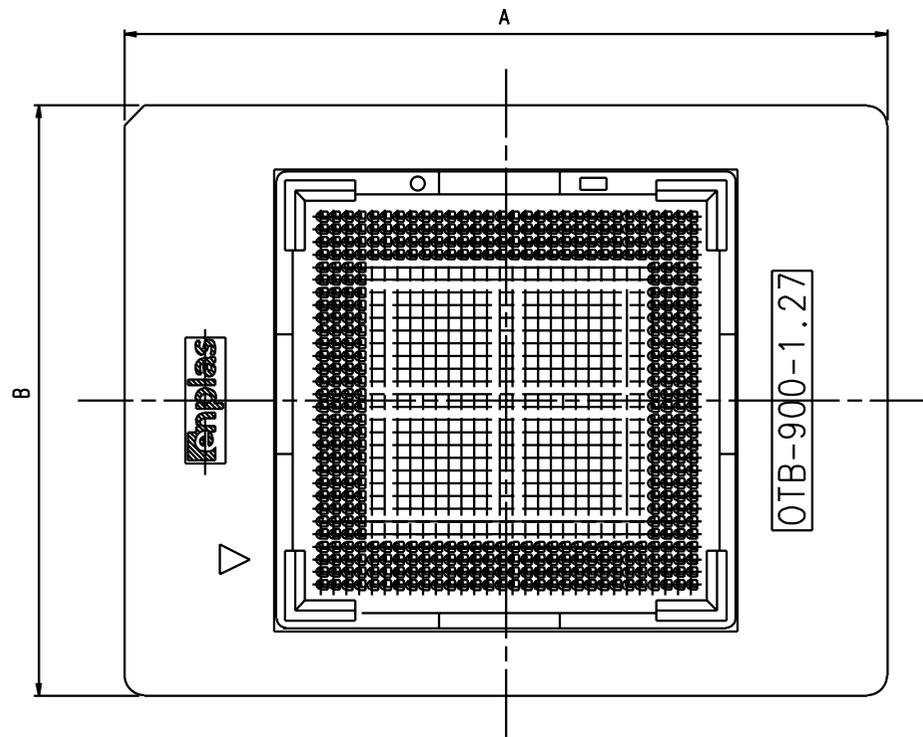
### OTB-900 SERIES (1.27mm PITCH)

Unit: mm

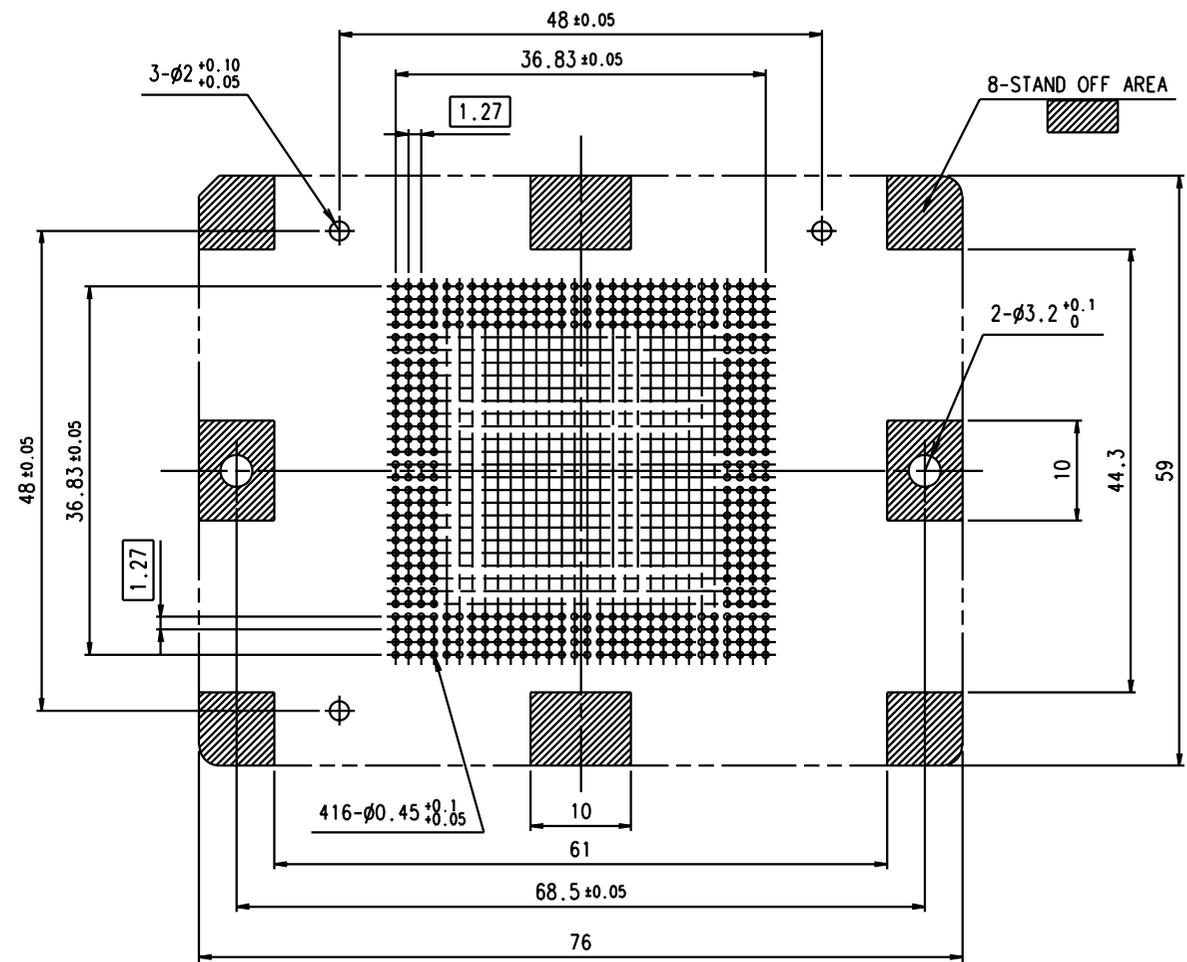
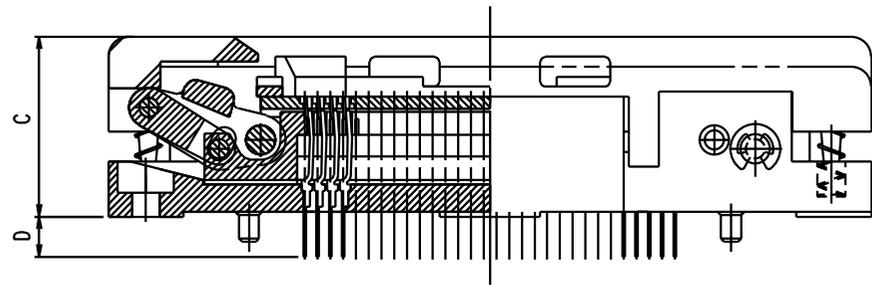
PART NO.	APPLICABLE IC DIMENSIONS (REF.)					OUTSIDE DIMENSIONS (REF.)				REMARKS
	BODY SIZE	GRID	ROW/ARRAY	LEADS NUMBER	PITCH	A	B	C	D	
OTB-480(900)-1.27-14	37.5X37.5	29X29	P.5 ROW	480	1.27	76	59	18	2.8	TBGA Cavity Down
OTB-596(900)-1.27-02	35X35	26X26	Depopulated	596	1.27	76	59	18	2.8	PBGA
OTB-400(900)-1.27-05	37.5X37.5	29X29	Depopulated	400	1.27	76	59	18	2.8	
OTB-549(900)-1.27-06	37.5x37.5	29x29	Depopulated	549	1.27	76	59	18	2.8	
OTB-760(676)-1.27-03	40X40	30X30	Depopulated	760	1.27	76	59	18	4	

– Depopulated version available.

– P=PERIPHERAL



MATCHING DEVICE  
(REFERENCE ONLY)



P.C.B. PATTERN  
OTB-416(900)-1.27 (REFERENCE ONLY)